

**INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)**

ATTY. DOCKET NO.
006217 USA/
Consilium/Consilium

SERIAL NO.
09/927,444

APPLICANT
Nicholas A. WARD et al.

FILING DATE
August 13, 2001

GROUP
2125

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>M</i>	5,975,994	11/02/99	Sandhu et al.			06/11/97
<i>N</i>	6,113,462	09/05/00	Yang			12/18/97
<i>C</i>	6,277,014	08/21/01	Chen et al.			10/09/98

FOREIGN PATENT DOCUMENTS

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)


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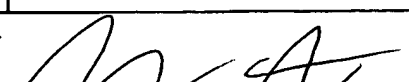
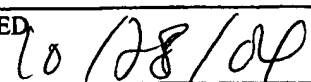
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
~	0 397 924 A1	11/22/90	Europe			X	
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	Rocha, Joao and Carlos Ramos. September 12, 1994. "Task Planning for Flexible and Agile Manufacturing Systems." <i>Intelligent Robots and Systems '94. Advanced Robotic Systems and the Real World, IROS '94. Proceedings of the IEEE/RSJ/GI International Conference on Munich, Germany 12-16 Sept. 1994.</i> New York, New York: IEEE. pp. 105-112.						
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~	September 26, 2002. Office Action for U.S. Serial No. 09/637,620, filed August 11, 2000.						
~	October 23, 2002. Office Action for U.S. Serial No. 09/469,227, filed December 22, 1999.						
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~	February 10, 2003. Office Action for U.S. Serial No. 09/619,044, filed July 19, 2000.						
~	April 9, 2003. Office Action for U.S. Serial No. 09/928,474, filed August 14, 2001.						
~	May 8, 2003. Office Action for U.S. Serial No. 09/637,620, filed August 11, 2000.						
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~	August 25, 2003. Office Action for U.S. Serial No. 10/100,184, filed March 19, 2002.						
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<p align="center">OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</p>			
SM	IslamRaja, M. M., C. Chang, J. P. McVittie, M. A. Cappelli, and K. C. Saraswat. May/June 1993. "Two Precursor Model for Low-Pressure Chemical Vapor Deposition of Silicon Dioxide from Tetraethylorthosilicate." <i>J. Vac. Sci. Technol. B</i> , Vol. 11, No. 3, pp. 720-726.		
CM	Kim, Eui Jung and William N. Gill. July 1994. "Analytical Model for Chemical Vapor Deposition of SiO ₂ Films Using Tetraethoxysilane and Ozone" (Abstract). <i>Journal of Crystal Growth</i> , Vol. 140, Issues 3-4, pp. 315-326.		
SM	Guo, R.S, A. Chen, C.L. Tseng, I.K. Fong, A. Yang, C.L. Lee, C.H. Wu, S. Lin, S.J. Huang, Y.C. Lee, S.G. Chang, and M.Y. Lee. June 16-17, 1998. "A Real-Time Equipment Monitoring and Fault Detection System." <i>Semiconductor Manufacturing Technology Workshop</i> , pp. 111-121.		
CM	Lantz, Mikkel. 1999. "Equipment and APC Integration at AMD with Workstream." <i>IEEE</i> , pp. 325-327.		
SM	July 15, 2004. Office Action for U.S. Serial No. 10/172,977, filed June 18, 2002.		
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SM	August 9, 2004. Written Opinion for PCT Serial No. PCT/US02/19063.		
CM	August 18, 2004. International Preliminary Examination Report for PCT Serial No. PCT/US02/19116.		
CM	August 24, 2004. Office Action for U.S. Serial No. 10/135,405, filed May 1, 2002.		
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EXAMINER			<p>DATE CONSIDERED 10/28/09</p>

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SHEET 2 OF 5

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✓	4,957,605	09/18/90	Hurwitt et al.			04/17/89
✓	5,240,552	08/31/93	Yu et al.			12/11/91
✓	5,369,544	11/29/94	Mastrangelo			04/05/93
✓	5,444,837	08/22/95	Bomans et al.			12/29/93
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✓	5,871,805	02/16/99	Lemelson			04/08/96
✓	6,012,048	01/04/00	Gustin et al.			05/30/97
✓	6,037,664	03/14/00	Zhao et al.			03/31/98
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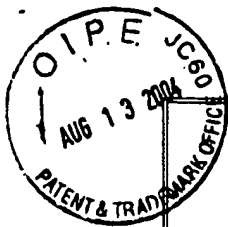
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~	6,317,643 B1	11/13/01	Dmochowski			03/31/99	
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M	EP 0 932 195 A1	07/28/99	EP			X	
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